

Amendments to the Abstract:

The abstract of the disclosure has been amended in the following manner:

~~An~~ Provided is an electronic parts mount apparatus for taking out semiconductor chips from a semiconductor wafer held on a wafer hold section by a transfer head comprising a plurality of suction nozzles and transporting and mounting the semiconductor chips to and on a board has a parts recognition camera disposed in a manner that it can advance to and retreat from the wafer hold section for picking up an image of the semiconductor wafer. Also provided is a method including a parts mounting step for mounting a plurality of semiconductor chips on the board by the transfer head and an image picking up step for picking up a plurality of semiconductor chips to be next taken out by the parts recognition camera which are performed concurrently. ~~Thereby, the number of electronic parts per mount turn can be increased, the tact time can be shortened, and the electronic parts can be efficiently taken out and mounted on the board.~~

Attachment: Replacement Sheet (clean-copy of abstract)